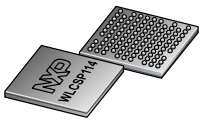

SOT2019-1

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

1 May 2020 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP114
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	24-04-2020
Manufacturer package code	98ASA01389D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.205	4.235	4.265	mm
package width	4.205	4.235	4.265	mm
package height	-	0.49	0.525	mm
nominal pitch	-	0.35	-	mm
actual quantity of termination	-	114	-	

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

2 Package outline

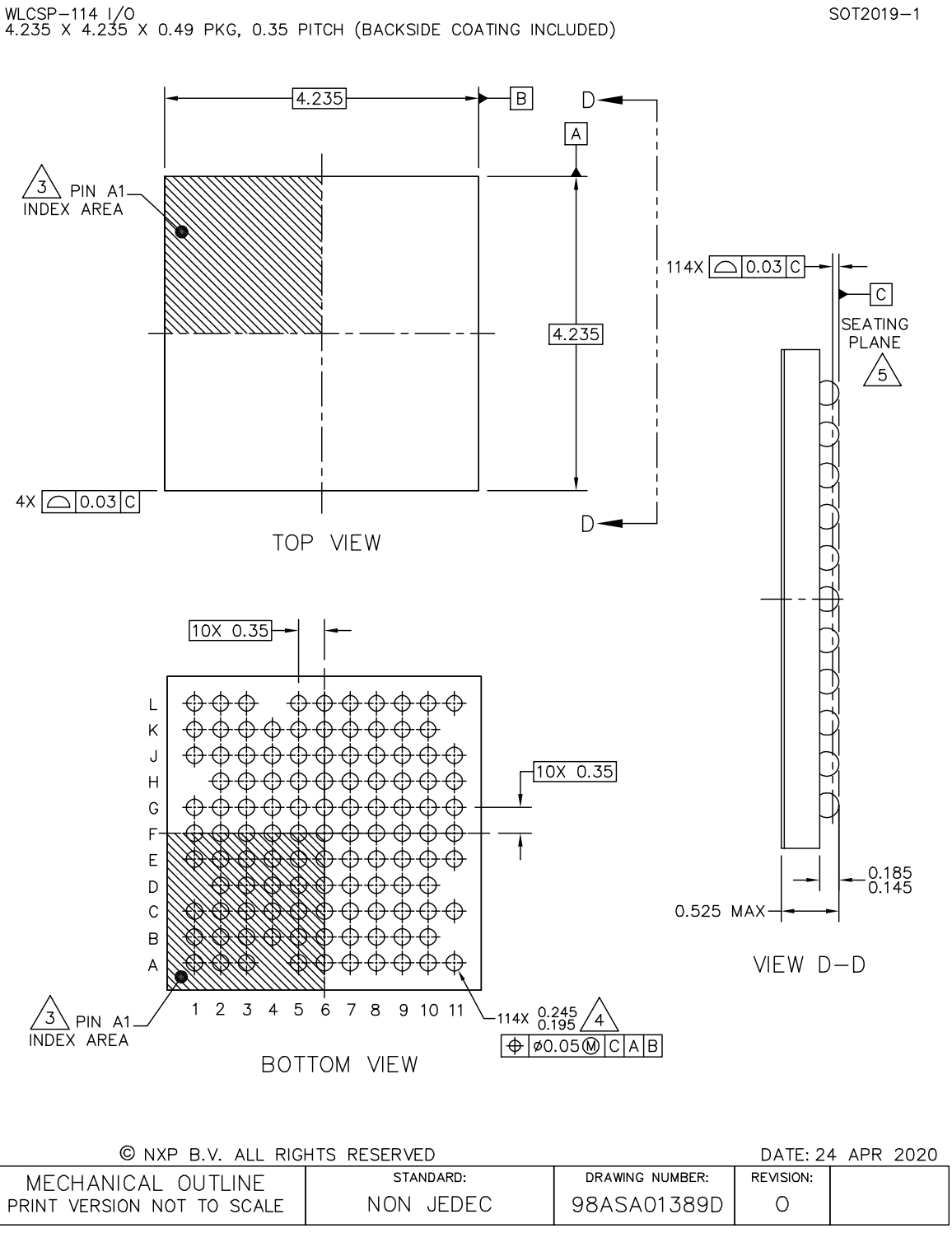

Figure 1. Package outline wlcsp114 (SOT2019-1)

3 Soldering

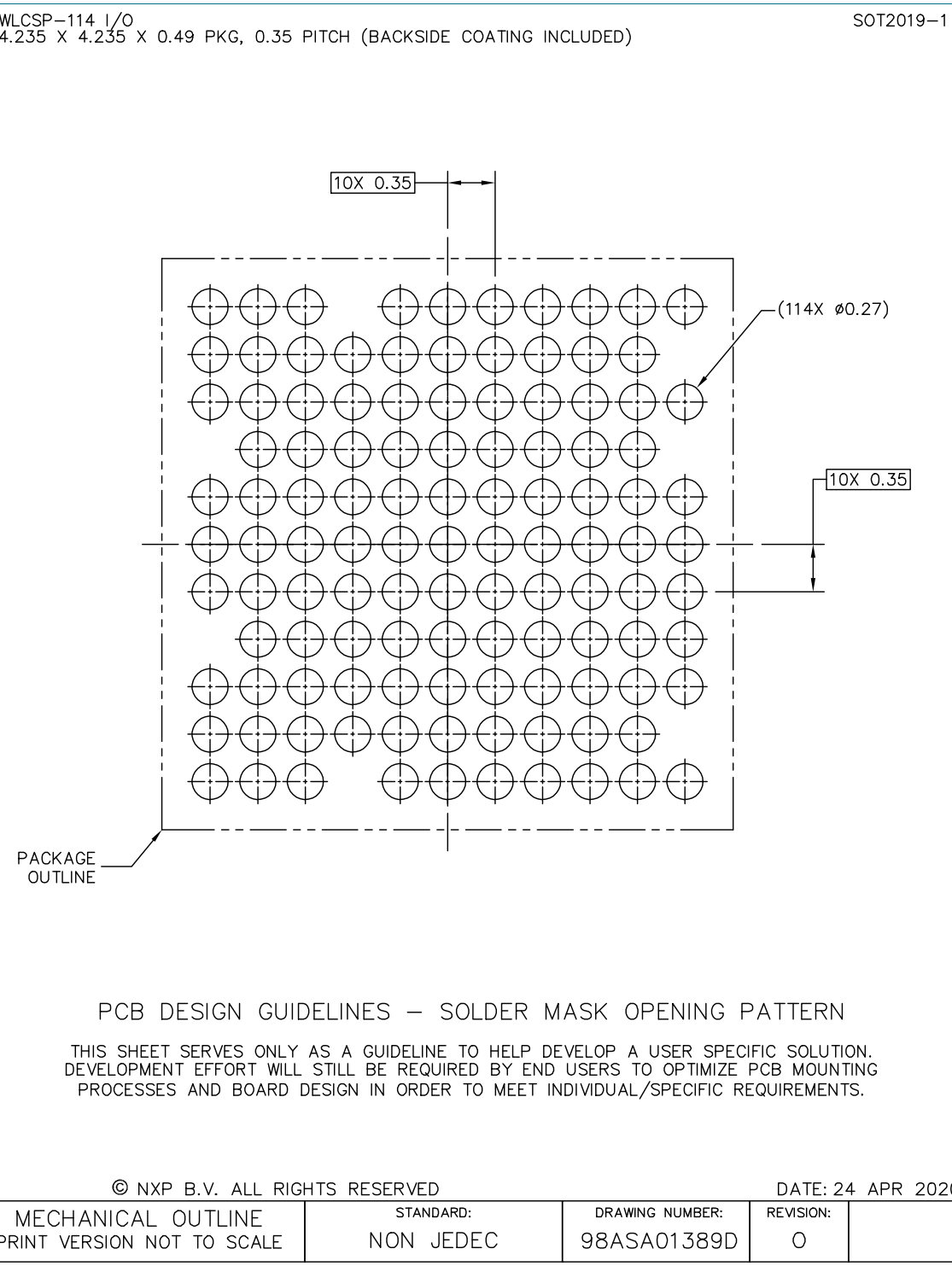

Figure 2. Reflow soldering footprint part1 for wlcsp114 (SOT2019-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

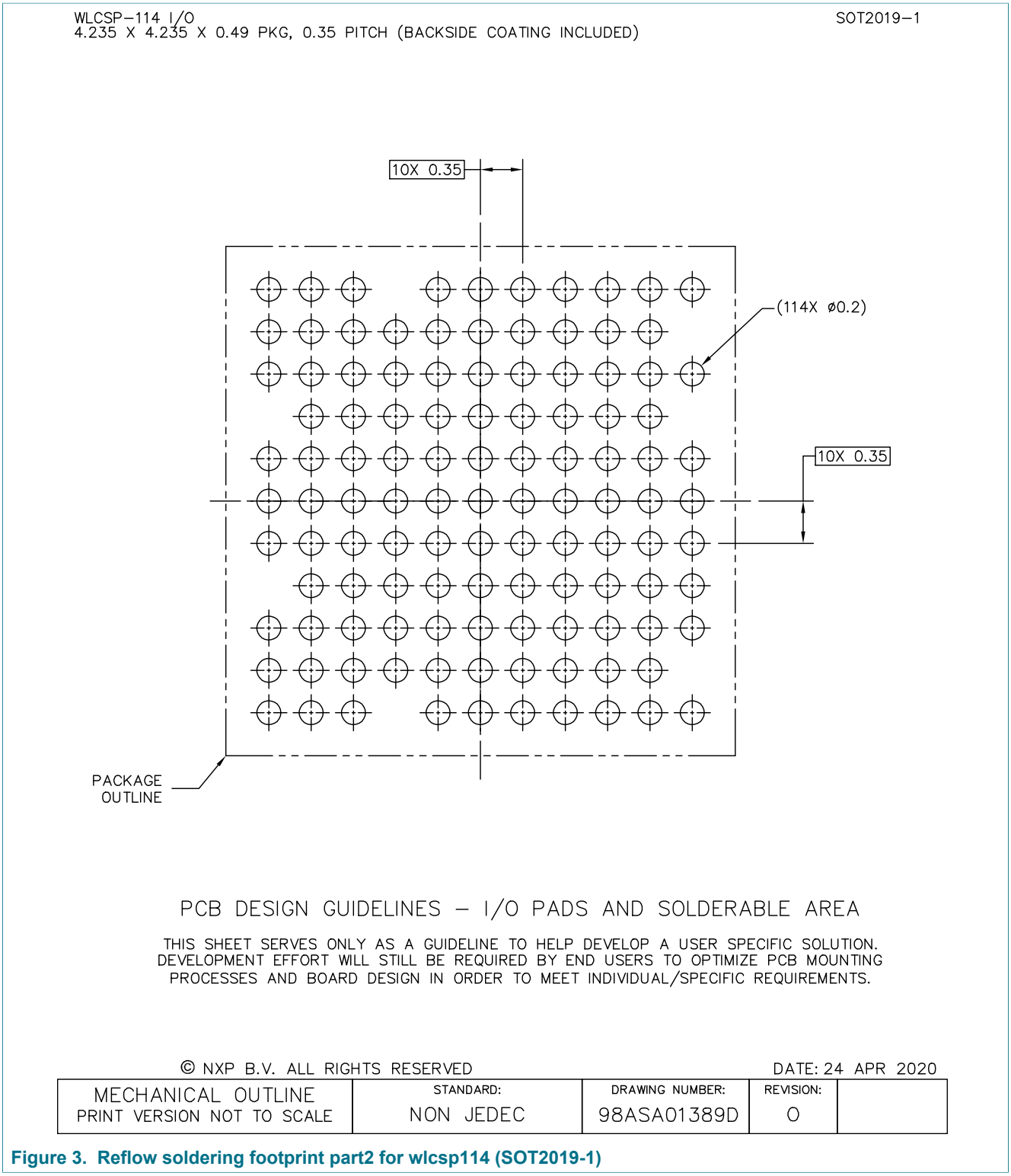

Figure 3. Reflow soldering footprint part2 for wlcsp114 (SOT2019-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

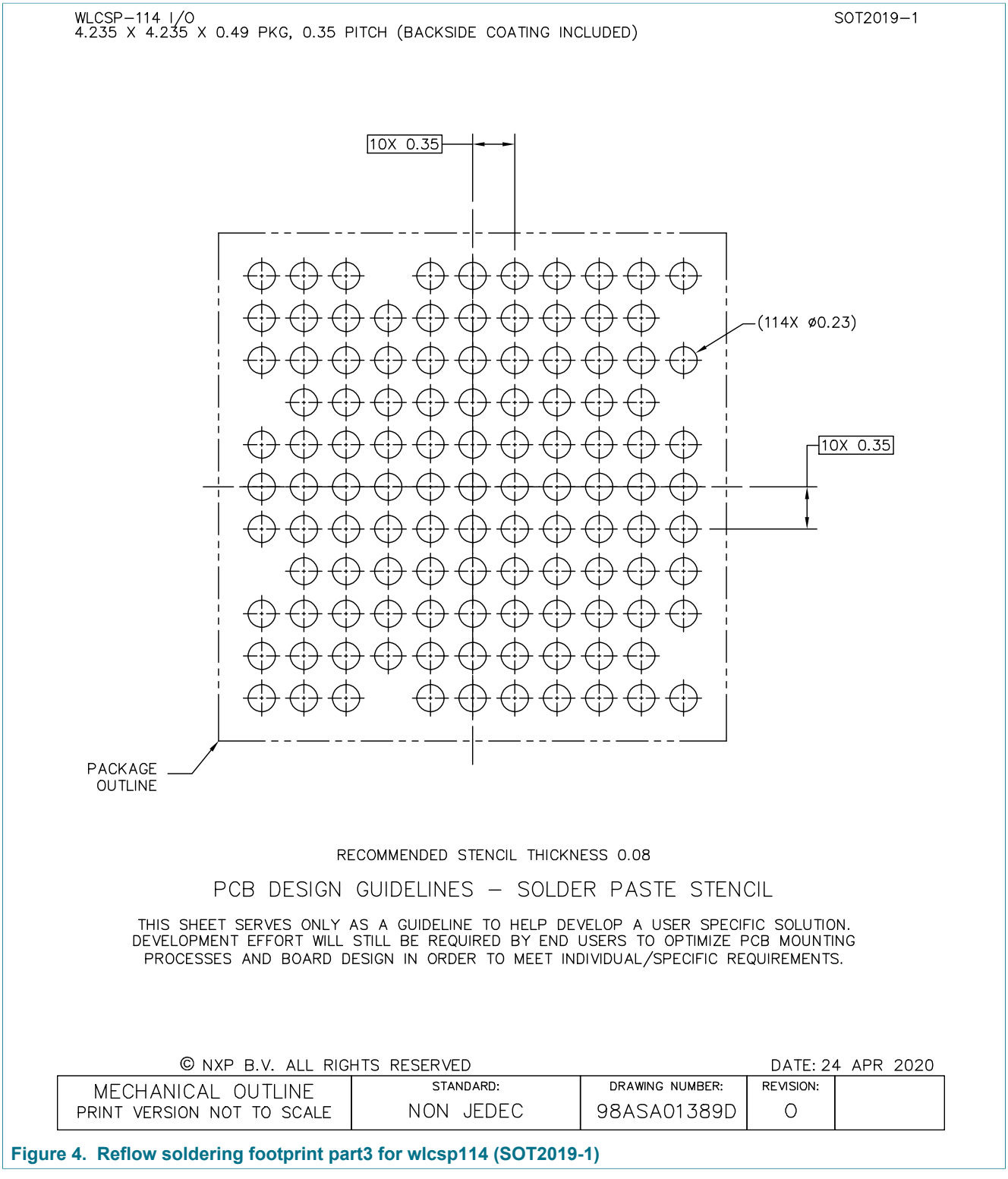

Figure 4. Reflow soldering footprint part3 for wlcsp114 (SOT2019-1)

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

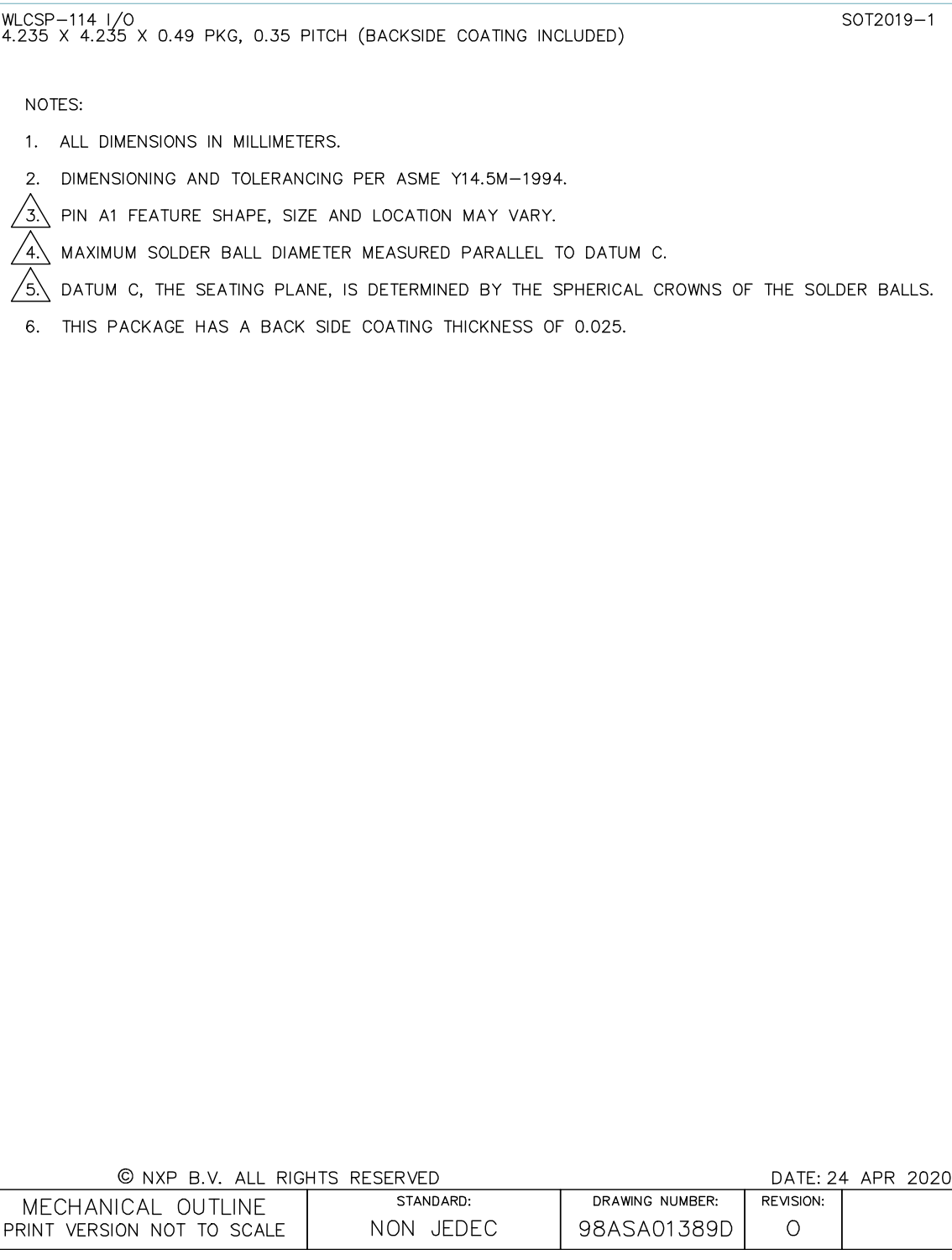

Figure 5. Package outline note wlcsp114 (SOT2019-1)

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SOT2019-1

WLCSP114, wafer level chip scale package, 114 terminals, 0.35 mm pitch, 4.235 mm x 4.235 mm x 0.49 mm body (backside coating included)

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Date of release: 1 May 2020